

## 1. General description

Planar passivated high commutation three quadrant triac in a SOT54 (TO-92) plastic package. This "series E" triac balances the requirements of commutation performance and gate sensitivity and is intended for interfacing with low power drivers and logic ICs including microcontrollers.

## 2. Features and benefits

- 3Q technology for improved noise immunity
- Direct gate triggering from low power drivers and logic ICs
- High commutation capability with sensitive gate
- High voltage capability
- Planar passivated for voltage ruggedness and reliability
- Sensitive gate for easy logic level triggering
- Triggering in three quadrants only

## 3. Applications

- Low power motor controls
- Small inductive loads e.g. solenoids, door locks, water valves
- Small loads in large white goods

## 4. Quick reference data

Table 1. Quick reference data

| Symbol                        | Parameter                            | Conditions  | Min | Typ | Max | Unit |
|-------------------------------|--------------------------------------|---|-----|-----|-----|------|
| $V_{DRM}$                     | repetitive peak off-state voltage    |   | -   | -   | 600 | V    |
| $I_{T(RMS)}$                  | RMS on-state current                 | full sine wave; $T_{lead} \leq 70\text{ °C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a> | -   | -   | 0.8 | A    |
| $I_{TSM}$                     | non-repetitive peak on-state current | full sine wave; $T_{j(init)} = 25\text{ °C}$ ; $t_p = 20\text{ ms}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>   | -   | -   | 9   | A    |
|                               |                                      | full sine wave; $T_{j(init)} = 25\text{ °C}$ ; $t_p = 16.7\text{ ms}$   | -   | -   | 9.9 | A    |
| $T_j$                         | junction temperature                 |   | -   | -   | 125 | °C   |
| <b>Static characteristics</b> |                                      |   |     |     |     |      |
| $I_{GT}$                      | gate trigger current                 | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G+; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a>                      | 0.5 | -   | 10  | mA   |
|                               |                                      | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G-; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a>                      | 0.5 | -   | 10  | mA   |

| Symbol                         | Parameter                             | Conditions   | Min | Typ  | Max | Unit       |
|--------------------------------|---------------------------------------|--|-----|------|-----|------------|
|                                |                                       | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G-;<br>$T_j = 25\text{ °C}$ ; Fig. 7  | 0.5 | -    | 10  | mA         |
| $I_H$                          | holding current                       | $V_D = 12\text{ V}$ ; $T_j = 25\text{ °C}$ ; Fig. 9  | -   | -    | 12  | mA         |
| $V_T$                          | on-state voltage                      | $I_T = 0.85\text{ A}$ ; $T_j = 25\text{ °C}$ ; Fig. 10   | -   | 1.35 | 1.6 | V          |
| <b>Dynamic characteristics</b> |                                       |  |     |      |     |            |
| $dV_D/dt$                      | rate of rise of off-state voltage     | $V_{DM} = 402\text{ V}$ ; $T_j = 125\text{ °C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit                    | 600 | -    | -   | V/ $\mu$ s |
| $dI_{com}/dt$                  | rate of change of commutating current | $V_D = 400\text{ V}$ ; $T_j = 125\text{ °C}$ ;<br>$I_{T(RMS)} = 0.8\text{ A}$ ; $dV_{com}/dt = 10\text{ V}/\mu\text{s}$ ;<br>gate open circuit | 1.6 | -    | -   | A/ms       |

## 5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description     | Simplified outline  | Graphic symbol   |
|-----|--------|-----------------|---|--|
| 1   | T2     | main terminal 2 |  <p>TO-92 (SOT54)</p> |  <p>sym051</p> |
| 2   | G      | gate            |   |  |
| 3   | T1     | main terminal 1 |   |  |

## 6. Ordering information

Table 3. Ordering information

| Type number  | Package |   |         |
|--------------|---------|---|---------|
|              | Name    | Description   | Version |
| BTA2008-600E | TO-92   | plastic single-ended leaded (through hole) package; 3 leads | SOT54   |

## 7. Limiting values

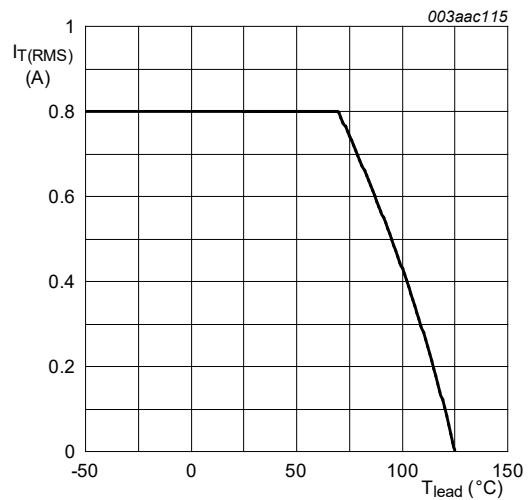
**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol       | Parameter                            | Conditions  | Min | Max  | Unit                   |
|--------------|--------------------------------------|---|-----|------|------------------------|
| $V_{DRM}$    | repetitive peak off-state voltage    |   | -   | 600  | V                      |
| $I_{T(RMS)}$ | RMS on-state current                 | full sine wave; $T_{lead} \leq 70\text{ }^{\circ}\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a> | -   | 0.8  | A                      |
| $I_{TSM}$    | non-repetitive peak on-state current | full sine wave; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$ ; $t_p = 20\text{ ms}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>   | -   | 9    | A                      |
|              |                                      | full sine wave; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$ ; $t_p = 16.7\text{ ms}$   | -   | 9.9  | A                      |
| $I^2t$       | $I^2t$ for fusing                    | $t_p = 10\text{ ms}$ ; SIN  | -   | 0.41 | $\text{A}^2\text{s}$   |
| $di_T/dt$    | rate of rise of on-state current     | $I_G = 20\text{ mA}$  | -   | 100  | $\text{A}/\mu\text{s}$ |
| $I_{GM}$     | peak gate current                    |   | -   | 1    | A                      |
| $P_{GM}$     | peak gate power                      |   | -   | 2    | W                      |
| $P_{G(AV)}$  | average gate power                   | over any 20 ms period   | -   | 0.1  | W                      |
| $T_{stg}$    | storage temperature                  |   | -40 | 150  | $^{\circ}\text{C}$     |
| $T_j$        | junction temperature                 |   | -   | 125  | $^{\circ}\text{C}$     |



**Fig. 1. RMS on-state current as a function of surge duration; maximum values**



**Fig. 2. RMS on-state current as a function of lead temperature; maximum values**

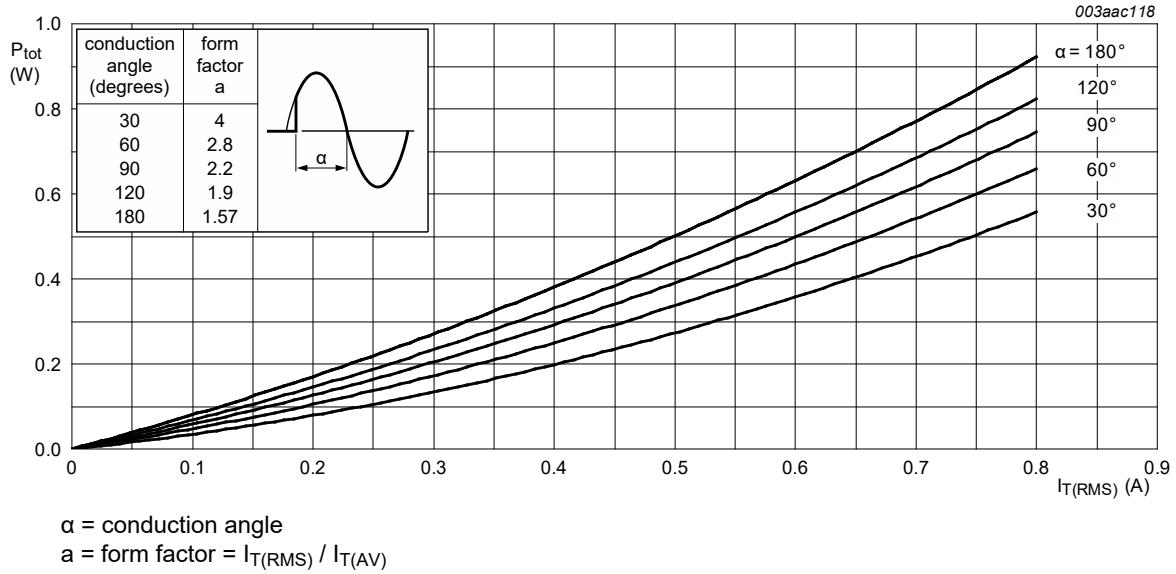


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

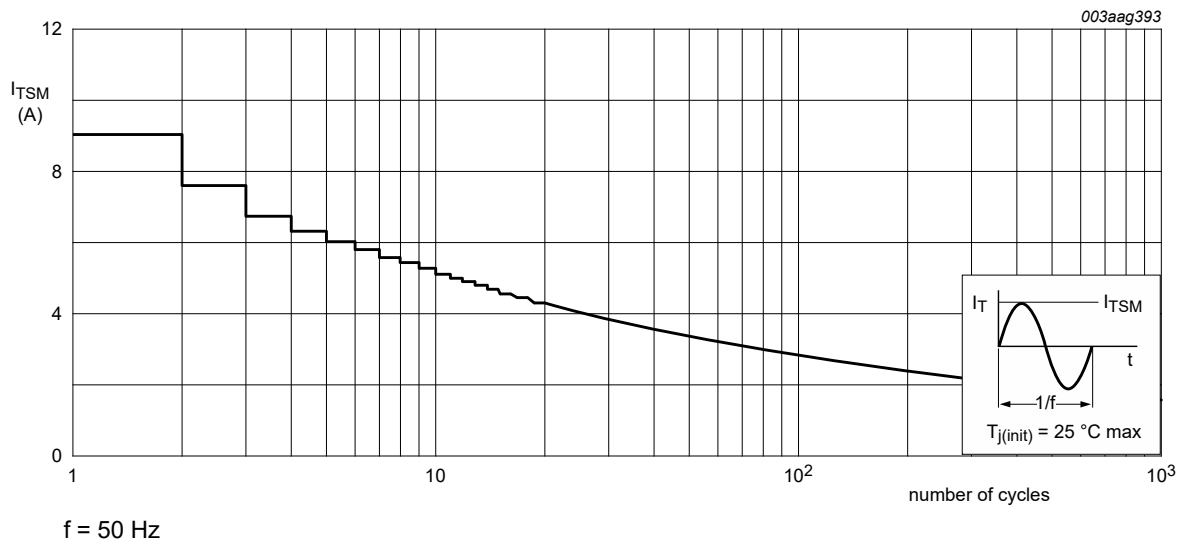
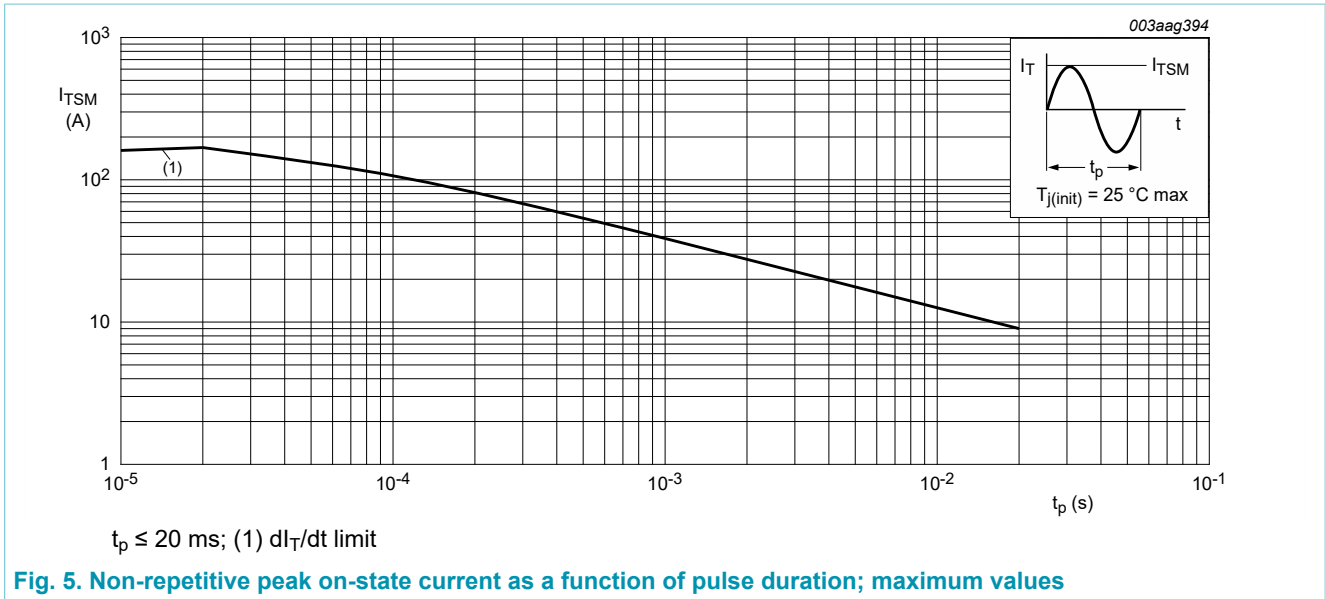


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



## 8. Thermal characteristics

Table 5. Thermal characteristics

| Symbol           | Parameter  | Conditions  | Min | Typ | Max | Unit |
|------------------|--|---|-----|-----|-----|------|
| $R_{th(j-lead)}$ | thermal resistance from junction to lead             | full cycle; <a href="#">Fig. 6</a>                | -   | -   | 60  | K/W  |
| $R_{th(j-a)}$    | thermal resistance from junction to ambient free air | printed circuit board mounted: lead length = 4 mm | -   | 150 | -   | K/W  |



Fig. 6. Transient thermal impedance from junction to lead as a function of pulse width

## 9. Characteristics

Table 6. Characteristics

| Symbol                         | Parameter                             | Conditions   | Min | Typ  | Max | Unit             |
|--------------------------------|---------------------------------------|--|-----|------|-----|------------------|
| <b>Static characteristics</b>  |                                       |  |     |      |     |                  |
| $I_{GT}$                       | gate trigger current                  | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G+;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>  | 0.5 | -    | 10  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G-;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>  | 0.5 | -    | 10  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G-;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>  | 0.5 | -    | 10  | mA               |
| $I_L$                          | latching current                      | $V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2+ G+;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a>  | -   | -    | 12  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2+ G-;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a>  | -   | -    | 20  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2- G-;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a>  | -   | -    | 12  | mA               |
| $I_H$                          | holding current                       | $V_D = 12\text{ V}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 9</a>  | -   | -    | 12  | mA               |
| $V_T$                          | on-state voltage                      | $I_T = 0.85\text{ A}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 10</a>   | -   | 1.35 | 1.6 | V                |
| $V_{GT}$                       | gate trigger voltage                  | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 25\text{ }^\circ\text{C}$ ;<br><a href="#">Fig. 11</a>   | -   | 0.9  | 1.5 | V                |
|                                |                                       | $V_D = 400\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 125\text{ }^\circ\text{C}$ ;<br><a href="#">Fig. 11</a>   | 0.2 | 0.3  | -   | V                |
| $I_D$                          | off-state current                     | $V_D = 600\text{ V}$ ; $T_j = 125\text{ }^\circ\text{C}$   | -   | 0.1  | 0.5 | mA               |
| <b>Dynamic characteristics</b> |                                       |  |     |      |     |                  |
| $dV_D/dt$                      | rate of rise of off-state voltage     | $V_{DM} = 402\text{ V}$ ; $T_j = 125\text{ }^\circ\text{C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit                    | 600 | -    | -   | V/ $\mu\text{s}$ |
| $dI_{com}/dt$                  | rate of change of commutating current | $V_D = 400\text{ V}$ ; $T_j = 125\text{ }^\circ\text{C}$ ;<br>$I_{T(RMS)} = 0.8\text{ A}$ ; $dV_{com}/dt = 10\text{ V}/\mu\text{s}$ ;<br>gate open circuit | 1.6 | -    | -   | A/ms             |



- (1) T2- G-
- (2) T2+ G-
- (3) T2+ G+

Fig. 7. Normalized gate trigger current as a function of junction temperature

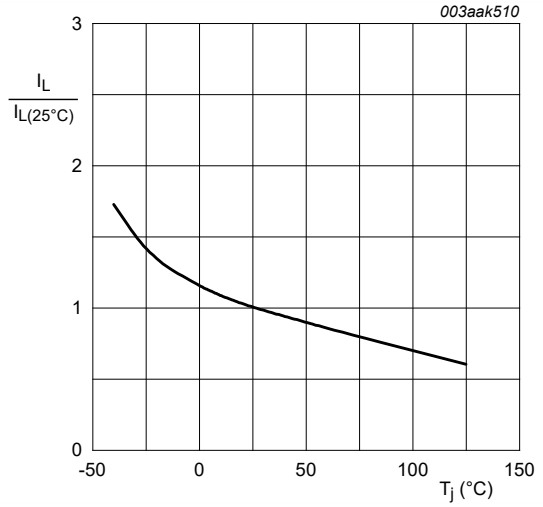


Fig. 8. Normalized latching current as a function of junction temperature

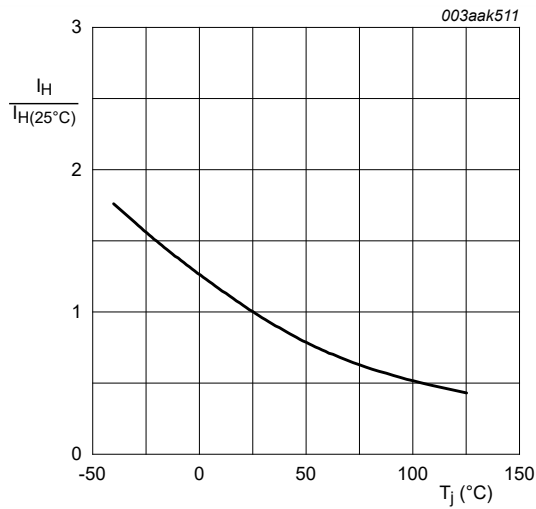
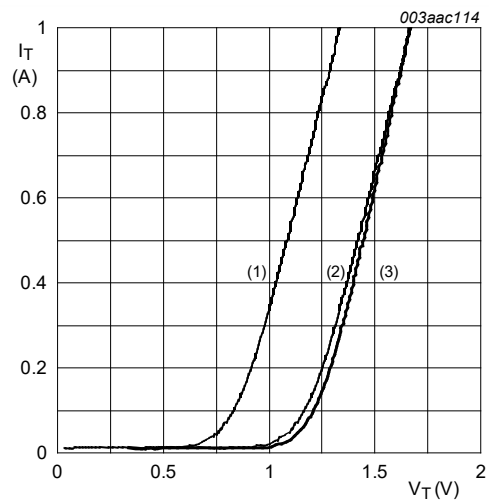


Fig. 9. Normalized holding current as a function of junction temperature



$V_o = 0.835 \text{ V}; R_s = 0.50 \Omega$

- (1)  $T_j = 125^{\circ}\text{C}$ ; typical values
- (2)  $T_j = 125^{\circ}\text{C}$ ; maximum values
- (3)  $T_j = 25^{\circ}\text{C}$ ; maximum values

Fig. 10. On-state current as a function of on-state voltage



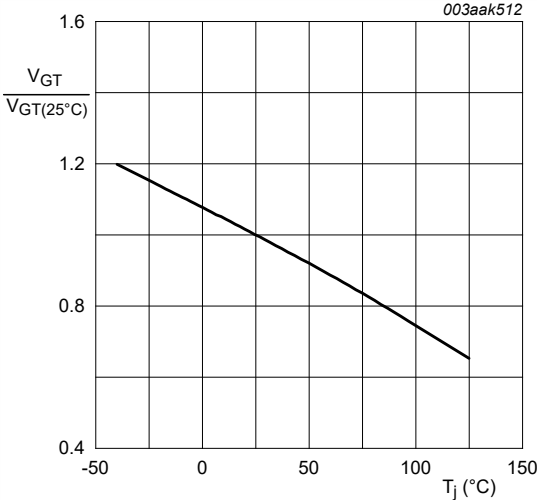


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

### 10. Package outline



**Fig. 12. Package outline TO-92 (SOT54)**

# 11. Legal information

## Data sheet status

| Document status [1][2]         | Product status [3] | Definition  |
|--------------------------------|--------------------|---|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
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